



# ICM&P 2025

2<sup>nd</sup> JSME International Conference on Materials & Processing,  
ICM&P 2025

Nov. 3<sup>rd</sup>- 6<sup>th</sup>, 2025

## 2nd Circular

### Guam, USA

### Hilton HOTELS & RESORTS

202 Hilton Road Tumon Bay, 96913  
Guam

#### Key dates

April 30<sup>th</sup>

400 Words Abstract

June 30<sup>th</sup>

Full paper submission

Aug. 31<sup>st</sup>

Early registration

#### Special Issue

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#### Conference overview

The International Conference on Materials & Processing is the premier international conference in the field of engineering on advanced materials and processing, sponsored by Japan Society of Mechanical Engineers (JSME), encouraging the exploration of collaborative research and technology transfer and promotes professional networking among scientists, technologists, and manufacturers.

#### Technical Symposia

The conference is highlighted, but are not limited to;

Symposia 1: Materials

Symposia 2: Processing

Symposia 3: Micro & Nano Technologies

Symposia 4: Properties, Applications & Systems

Symposia 5: Sustainable Manufacturing

#### Registration fees (tentative)

Normal	\$700 (Early bird)	\$850 (Standard)
Student	\$350 (Early bird)	\$450 (Standard)

#### Organizing committee

Conference Chair: S. Kobayashi Tokyo Metropolitan Univ.

Conference Co-Chair: Y. Yamazaki Chiba Univ.

#### Executive Committee:

Chair: Y. Yamazaki Chiba Univ.

Co-Chair: H. Nakatani Osaka Metropolitan Univ.

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日本機械学会



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## Plenary lecture



Prof. Wei-Chung Wan  
National Taiwan University



Prof. Seiichi Hata  
Nagoya University



Prof. Seong Su Kim  
Korea Advanced Institute  
of Science and Technology



Prof. Jian-Feng Wen  
East China University of  
Science and Technology